

METHOD OF FORMING A BOND PAD ON AN I/C CHIP AND RESULTING STRUCTURE

ABSTRACT OF THE DISCLOSURE

5 A method of forming wire bonds in (I/C) chips comprising: providing an I/C chip
having a conductive pad for a wire bond with at least one layer of dielectric material
overlying the pad; forming an opening through the dielectric material exposing a portion
of said pad. Forming at least a first conductive layer on the exposed surface of the pad
and on the surface of the opening. Forming a seed layer on the first conductive layer;
10 applying a photoresist over the seed layer; exposing and developing the photoresist
revealing the surface of the seed layer surrounding the opening; removing the exposed
seed layer; removing the photoresist material in the opening revealing the seed layer.
Plating at least one second layer of conductive material on the seed layer in the opening,
and removing the first conductive layer on the dielectric layer around the opening. The
15 invention also includes the resulting structure.